

Pb-free HEAT

3863X Series

Single Color φ3 Flush Mount Round Shape Type

Features

Package	Φ3 Round shape type, YPY : Pale Yellow Clear epoxy FA : Pale Orange Clear epoxy FR : Pale Red Clear epoxy
Product features	• Outer Dimension φ3 Flush Mount Round shape type • Operation temperature range. Storage Temperature :-40℃～100℃ Operating Temperature :-40℃～85℃ • Lead-free soldering compatible • RoHS compliant
Dominant wavelength	Yellow Green : 572nm (YPY) Orange : 605nm (FA) Red : 626nm (FR)
Half Intensity Angle	YPY,FA,FR : 20 deg.
Die materials	YPY,FA,FR : AlGaInP
Rank grouping parameter	Sorted by luminous intensity per rank taping
Soldering methods	TTW (Through The Wave) soldering and manual soldering
ESD	AlGaInP : More than 2kV(HBM)
Packing	Bulk : 200pcs(MIN.)

Recommended Applications

Amusement Equipment, Electric Household Appliances, OA/FA, Other General Applications

Color and Luminous Intensity

(Ta=25℃)

Part No.	Material	Emitted Color	Lens Color		Dominant Wavelength λ d (nm)		Luminous Intensity Iv (mcd)		
					TYP.	I_F	MIN.	TYP.	I_F
YPY3863X	AlGaInP	Yellow Green	Palle Yellow	Clear	572	20	180	360	20
FA3863X	AlGaInP	Orange	Pale Orange		605	20	400	800	20
FR3863X	AlGaInP	Red	Pale Red		626	20	320	640	20

Absolute Maximum Ratings

(Ta=25℃)

Item	Symbol	Absolute Maximum Ratings			Unit
		YPY	FA	FR	
Power Dissipation	P_d	130	125	125	mW
Forward Current	I_F	50	50	50	mA
Pulse Forward Current ※1	I_{FRM}	200	200	200	mA
Derating (Ta=25℃ or higher)	ΔI_F	0.67	0.67	0.67	mA/℃
Reverse Voltage	V_R	5	5	5	V
Operating Temperature	T_{opr}	-40～+85			℃
Storage Temperature	T_{stg}	-40～+100			℃

※1 I_{FRM} Measurement condition : Pulse Width≦1ms., Duty≦1/20.

Electro-Optical Characteristics

(Ta=25℃)

Item	Conditions	Symbol	Characteristics				Unit
				YPY	FA	FR	
Forward Voltage	I_F=20mA	V_F	TYP.	2.1	1.9	1.9	V
			MAX.	2.5	2.4	2.4	
Reverse Current	V_R=5V	I_R	MAX.	100	100	100	μA
Peak Wavelength	I_F=20mA	λ_p	TYP.	575	609	635	nm
Dominant Wavelength	I_F=20mA	λ_d	TYP.	572	605	626	nm
Spectral Line Half Width	I_F=20mA	$\Delta\lambda$	TYP.	15	15	15	nm
Half Intensity Angle	I_F=20mA	$2\theta 1/2$	TYP.	20	20	20	deg.

Luminous Intensity Rank

(Ta=25℃)

Rank	I_V(mcd)						Condition
	YPY		FA		FR		
	MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	
A	180	360	400	800	320	640	I_F = 20mA
B	250	500	560	1,120	450	900	
C	360	780	800	1,600	640	1,280	
D	500	1,000	1,120	2,240	900	1,800	
E	780	-	1,600	-	1,280	-	

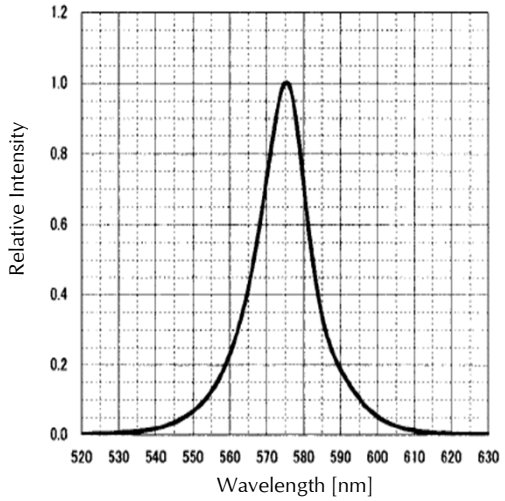
※Please contact our sales staff concerning rank designation.

Technical Data(**YPY**)

Spectral Distribution

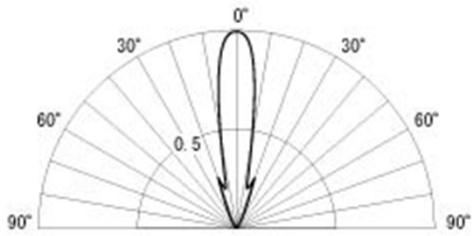
Relative Intensity vs. Wavelength

Condition : Ta = 25℃, I_F = 20mA



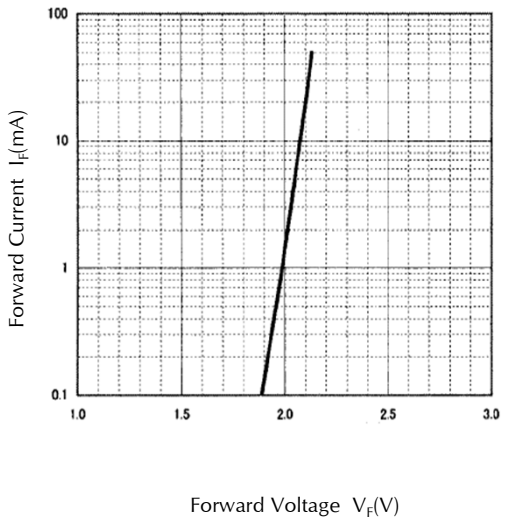
Spatial Distribution Example

Condition : Ta = 25℃



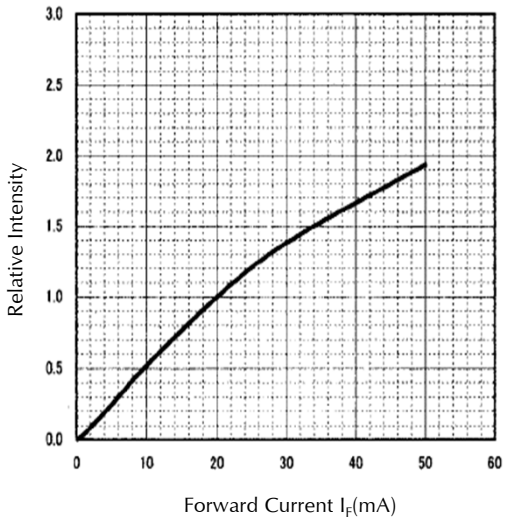
Forward Voltage vs. Forward Current

Condition : Ta = 25℃



Forward Current vs. Relative Intensity

Condition : Ta = 25℃

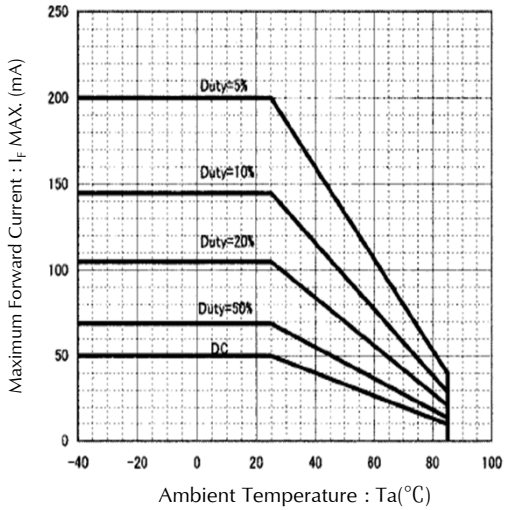


Technical Data(**YPY**)

Derating

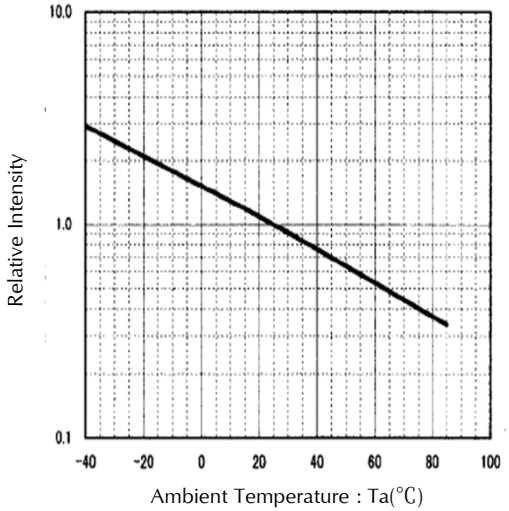
Ambient Temperature vs. Maximum Forward Current

Repetition Frequency : f ≧ 50Hz

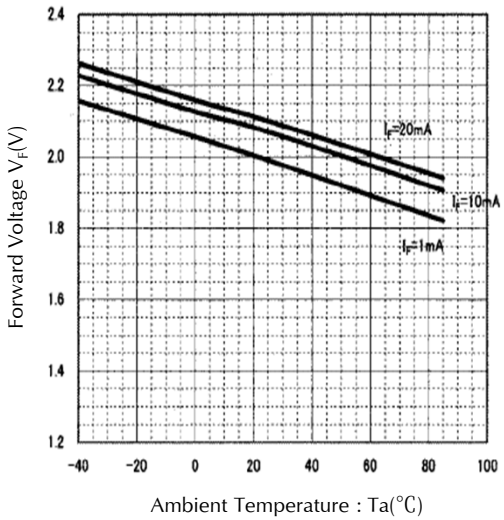


Ambient Temperature vs. Relative Intensity

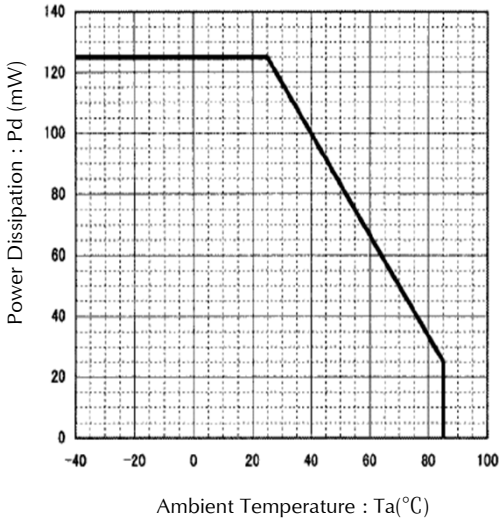
Condition : I_F=20mA



Ambient Temperature vs. Forward Voltage

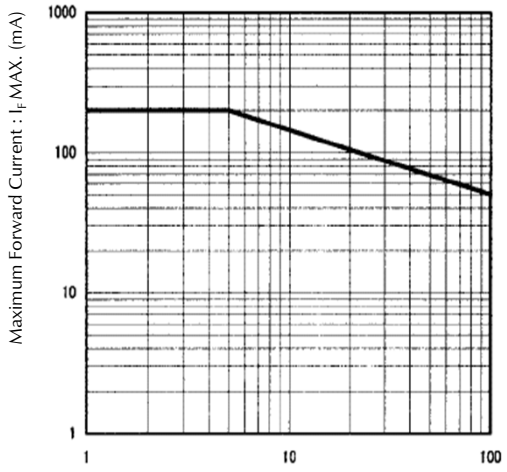


Power Dissipation vs. Ambient Temperature

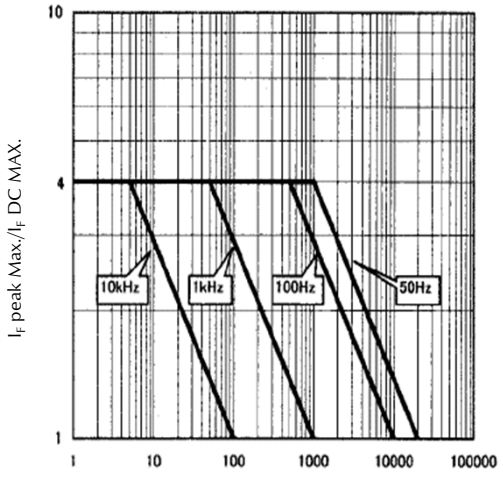


Technical Data(**YPY**)

Dynamic Drive Rating
Duty cycle vs. Maximum Forward Current
Condition : Ta = 25℃



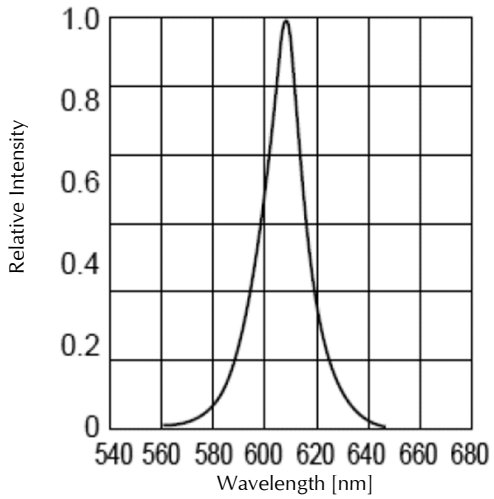
Pulse Width vs. Maximum Tolerable Peak Current
Condition : Ta = 25℃



Technical Data(**FA**)

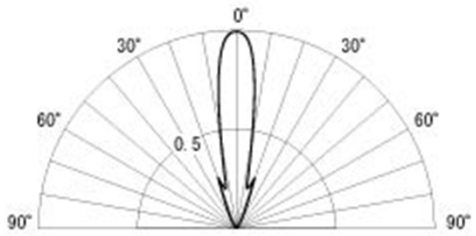
Spectral Distribution

Relative Intensity vs. Wavelength
Condition : Ta = 25℃, I_F = 20mA



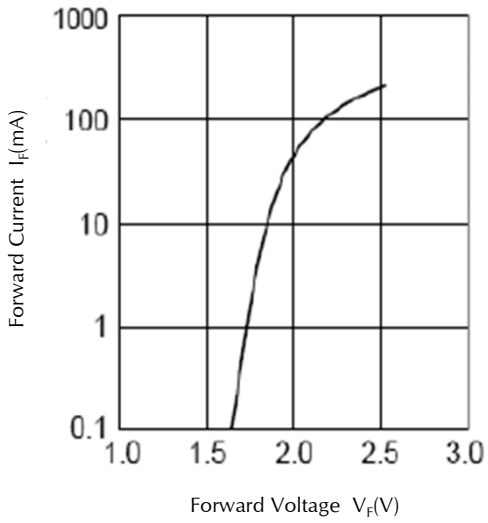
Spatial Distribution Example

Condition : Ta = 25℃



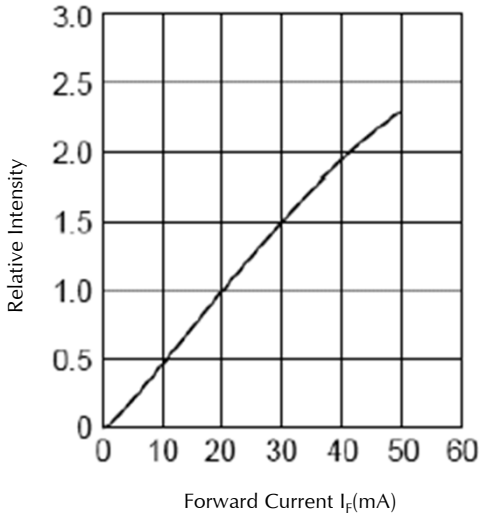
Forward Voltage vs. Forward Current

Condition : Ta = 25℃



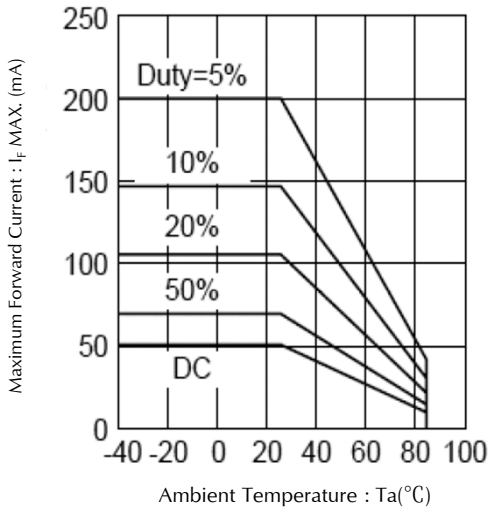
Forward Current vs. Relative Intensity

Condition : Ta = 25℃

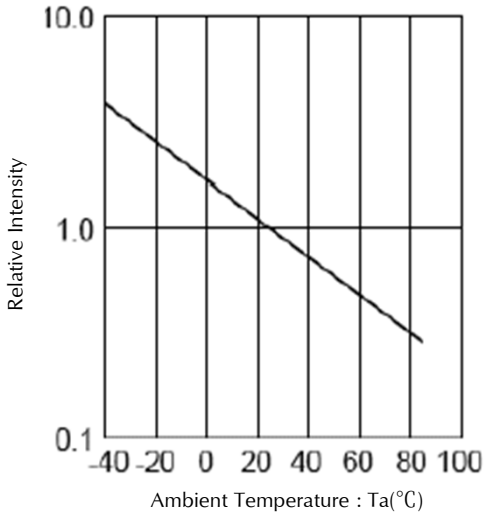


Technical Data(**FA**)

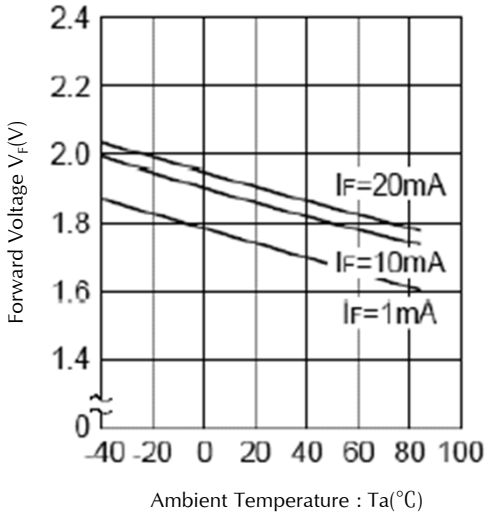
Derating
Ambient Temperature vs. Maximum Forward Current
Repetition Frequency : f ≧ 50Hz



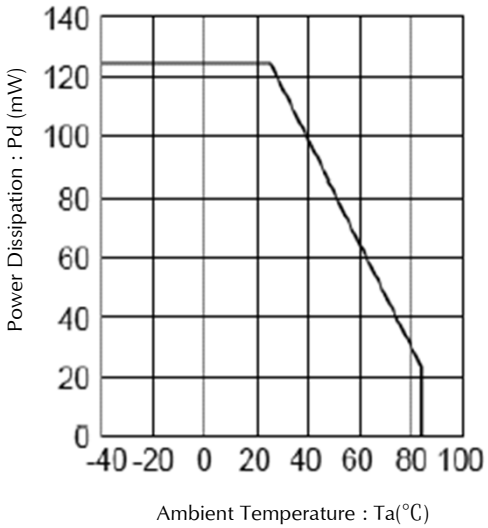
Ambient Temperature vs. Relative Intensity
Condition : I_F=20mA



Ambient Temperature vs. Forward Voltage

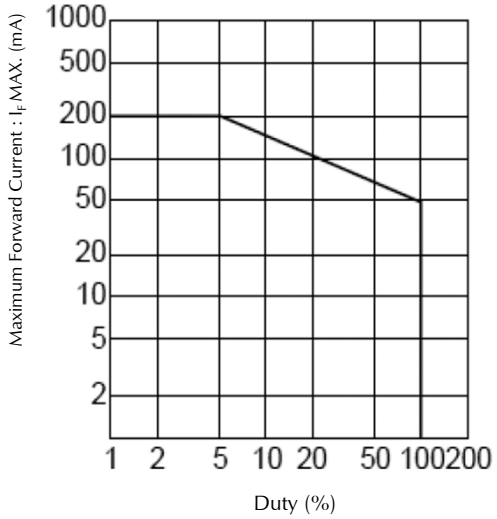


Power Dissipation vs. Ambient Temperature

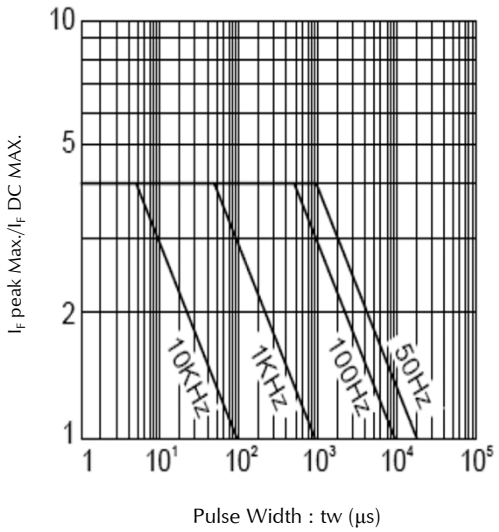


Technical Data(**FA**)

Dynamic Drive Rating
Duty cycle vs. Maximum Forward Current
Condition : Ta = 25℃



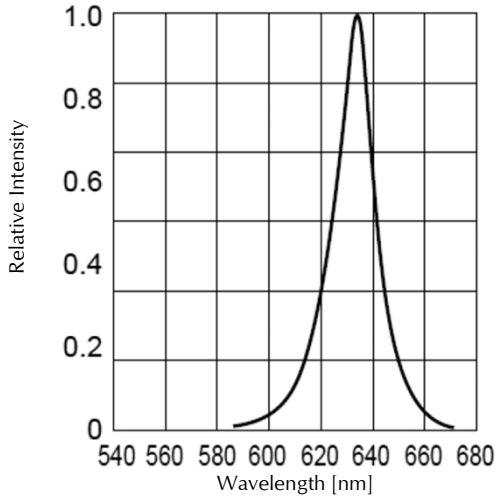
Pulse Width vs. Maximum Tolerable Peak Current
Condition : Ta = 25℃



Technical Data(**FR**)

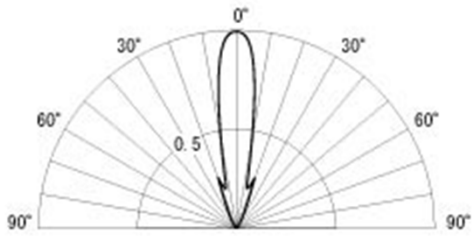
Spectral Distribution

Relative Intensity vs. Wavelength
Condition : Ta = 25℃, I_F = 20mA



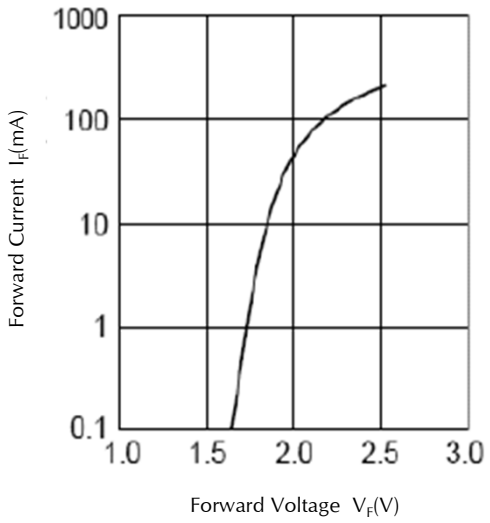
Spatial Distribution Example

Condition : Ta = 25℃



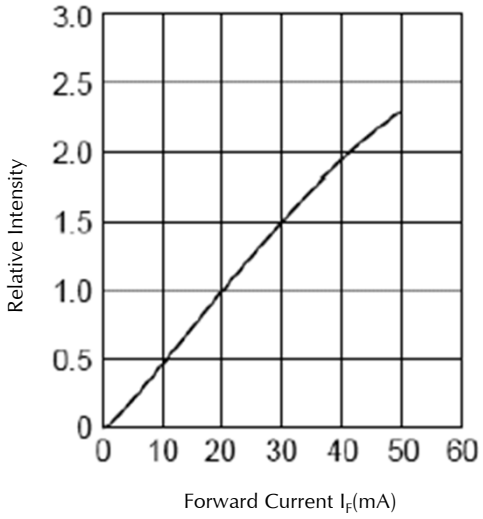
Forward Voltage vs. Forward Current

Condition : Ta = 25℃



Forward Current vs. Relative Intensity

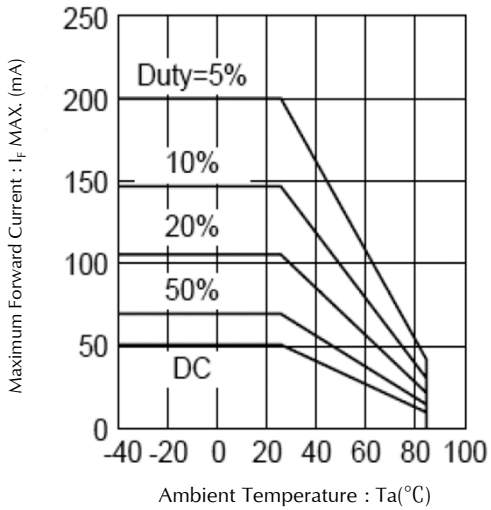
Condition : Ta = 25℃



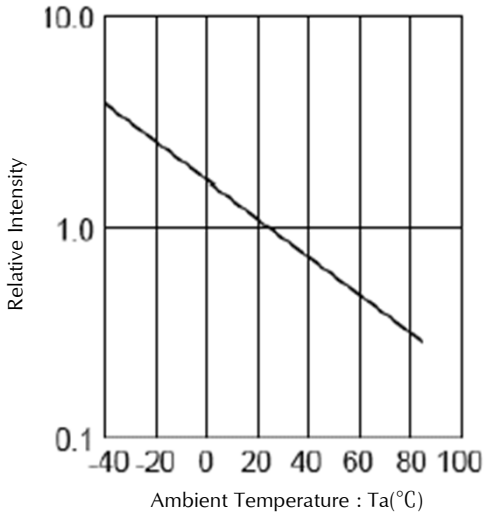
Technical Data(**FR**)

Derating

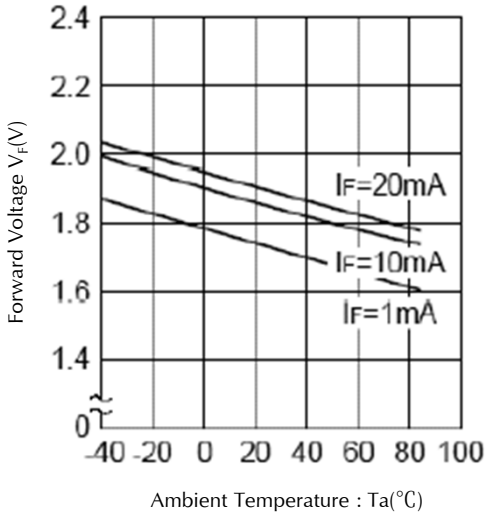
Ambient Temperature vs. Maximum Forward Current
Repetition Frequency : f ≧ 50Hz



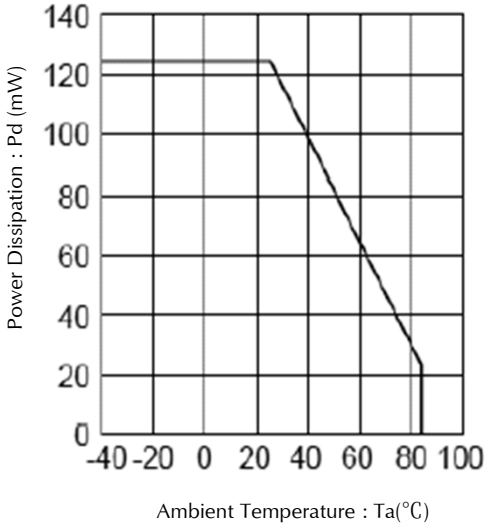
Ambient Temperature vs. Relative Intensity
Condition : I_F=20mA



Ambient Temperature vs. Forward Voltage

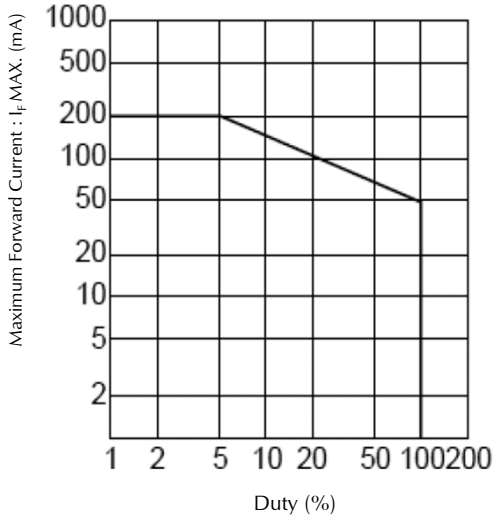


Power Dissipation vs. Ambient Temperature

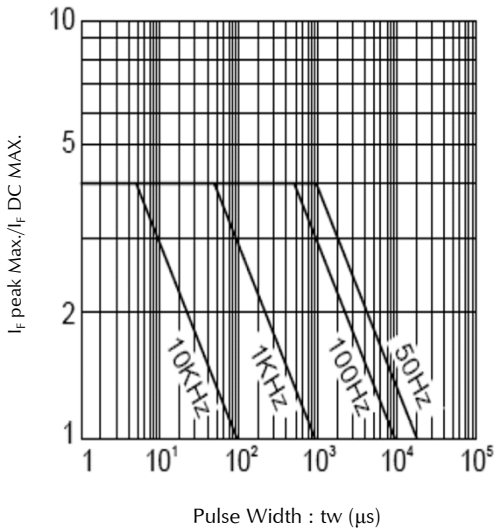


Technical Data(**FR**)

Dynamic Drive Rating
Duty cycle vs. Maximum Forward Current
Condition : Ta = 25℃



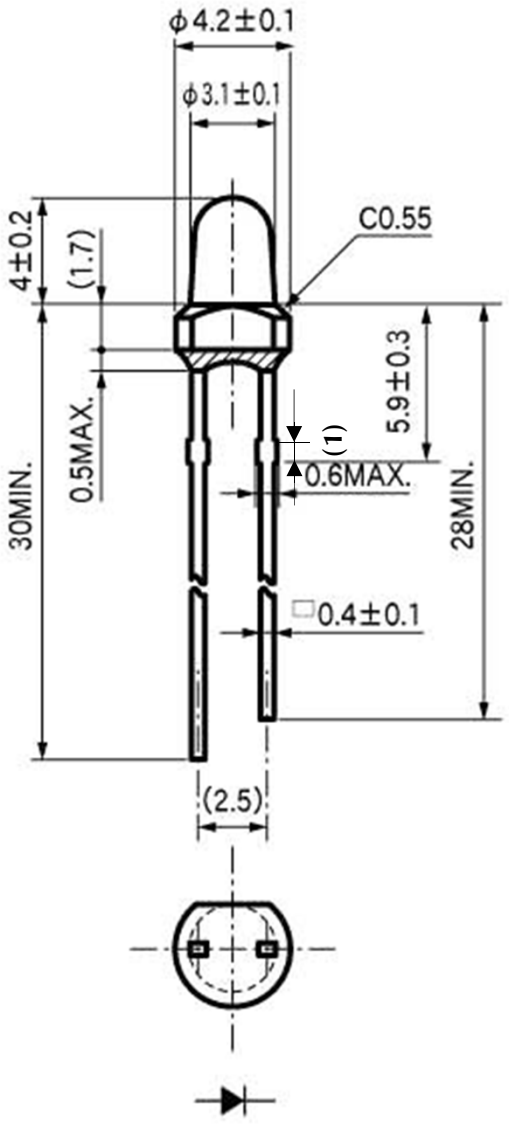
Pulse Width vs. Maximum Tolerable Peak Current
Condition : Ta = 25℃



Package Dimensions

(Unit: mm)

Mass : (0.16)g



TTW (Through The Wave) soldering Conditions

Pre-heating	100 ℃	(MAX.)
Solder Bath Temp.	265℃	(MAX.)
Dipping Time	5 s	(MAX.)

1) The dip soldering process shall be 2 times maximum.
2) The product shall be cooled to room temp. before the second dipping process.

※The detail is described to LED and Photodetector handling precautions of home page:
"Mounting through-hole Type Devices" and "Soldering", and use it after the confirmation, please.

Manual Soldering Conditions

Iron tip temp.	360℃	(MAX.)
Soldering time and frequency	3 s 2 times	(MAX.) (MAX.)

※The detail is described to LED and Photodetector handling precautions of home page:
"Mounting through-hole Type Devices" and "Soldering", and use it after the confirmation, please.

Reliability Testing Result

Reliability Testing Result	Applicable Standard	Testing Conditions	Duration	Failure
Room Temp. Operating Life	EIAJ ED-4701/100(101)	Ta = 25℃, I_F = Maxium Rated Current	1,000 h	0/25
Resistance to Soldering Heat	EIAJ ED-4701/300(302)	260±5℃, 1.6mm from package base	10s	0/25
Temperature Cycling	EIAJ ED-4701/100(105)	Minimum Rated Storage Temperature(30min) ～Normal Temperature(15min) ～Maximum Rated Storage Temperature(30min) ～Normal Temperature(15min)	5 cycles	0/25
Wet High Temp. Storage Life	EIAJ ED-4701/100(103)	Ta = 60±2℃, RH = 90±5%	1,000 h	0/25
High Temp. Storage Life	EIAJ ED-4701/200(201)	Ta = Maximum Rated Storage Temperature	1,000 h	0/25
Low Temp. Storage Life	EIAJ ED-4701/200(202)	Ta = Minimum Rated Storage Temperature	1,000 h	0/25
Lead Tension	EIAJ ED-4701/400(401)	10N,1time (□0.4 and Flat Package : 5N)	10s	0/10
Vibration, Variable Frequency	EIAJ ED-4701/400(403)	98.1m/s^2(10G), 100 ～ 2KHz sweep for 20min., XYZ each direction	2 h	0/10

Failure Criteria

Items	Symbols	Conditions	Failure criteria
Luminous Intensity	Iv	I_F Value of each product Luminous Intensity	Testing Min. Value < Spec. Min. Value x 0.5
Forward Voltage	V_F	I_F Value of each product Forward Voltage	Testing Max. Value ≧ Spec. Max. Value x 1.2
Reverse Current	I_R	V_R = Maximum Rated Reverse Voltage V	Testing Max. Value ≧ Spec. Max. Value x 2.5
Cosmetic Appearance	-	-	Occurrence of notable decoloration, deformation and cracking

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1) The technical information shown in the data sheets are limited to the typical characteristics and circuit examples of the referenced products. It does not constitute the warranting of industrial property nor the granting of any license.

2) For the purpose of product improvement, the specifications, characteristics and technical data described in the data sheets are subject to change without prior notice. Therefore it is recommended that the most updated specifications be used in your design.

3) When using the products described in the data sheets, please adhere to the maximum ratings for operating voltage, heat dissipation characteristics, and other precautions for use. We are not responsible for any damage which may occur if these specifications are exceeded.

4) The products that have been described to this catalog are manufactured so that they will be used for the electrical instrument of the benchmark (OA equipment, telecommunications equipment, AV machine, home appliance and measuring instrument).
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5) In order to export the products or technologies described in this data sheet which are under the "Foreign Exchange and Foreign Trade Control Law," it is necessary to first obtain an export permit from the Japanese government.

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